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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	234720
Number of Logic Elements/Cells	622000
Total RAM Bits	51200000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1517-BBGA, FCBGA
Supplier Device Package	1517-FBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxma7n3f40c2n

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

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Table 1. Stratix V GX and GS Commercial and Industrial Speed Grade Offering (1), (2), (3) (Part 2 of 2)

Transceiver Speed	Core Speed Grade										
Grade	C1	C2, C2L	C3	C4	12, 12L	13, 13L	I3YY	14			
3 GX channel—8.5 Gbps	_	Yes	Yes	Yes	_	Yes	Yes ⁽⁴⁾	Yes			

Notes to Table 1:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.
- (3) C2L, I2L, and I3L speed grades are for low-power devices.
- (4) I3YY speed grades can achieve up to 10.3125 Gbps.

Table 2 lists the industrial and commercial speed grades for the Stratix V GT devices.

Table 2. Stratix V GT Commercial and Industrial Speed Grade Offering (1), (2)

Transacius Crad Crado	Core Speed Grade							
Transceiver Speed Grade	C1	C2	12	13				
2 GX channel—12.5 Gbps GT channel—28.05 Gbps	Yes	Yes	_	_				
3 GX channel—12.5 Gbps GT channel—25.78 Gbps	Yes	Yes	Yes	Yes				

Notes to Table 2:

- (1) C = Commercial temperature grade; I = Industrial temperature grade.
- (2) Lower number refers to faster speed grade.

Absolute Maximum Ratings

Absolute maximum ratings define the maximum operating conditions for Stratix V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms. The functional operation of the device is not implied for these conditions.



Conditions other than those listed in Table 3 may cause permanent damage to the device. Additionally, device operation at the absolute maximum ratings for extended periods of time may have adverse effects on the device.

Table 3. Absolute Maximum Ratings for Stratix V Devices (Part 1 of 2)

Symbol	Description	Minimum	Maximum	Unit
V _{CC}	Power supply for core voltage and periphery circuitry	-0.5	1.35	V
V _{CCPT}	Power supply for programmable power technology	-0.5	1.8	V
V _{CCPGM}	Power supply for configuration pins	-0.5	3.9	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	-0.5	3.4	V
V _{CCBAT}	Battery back-up power supply for design security volatile key register	-0.5	3.9	V
V _{CCPD}	I/O pre-driver power supply	-0.5	3.9	V
V _{CCIO}	I/O power supply	-0.5	3.9	V

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Recommended Operating Conditions

This section lists the functional operating limits for the AC and DC parameters for Stratix V devices. Table 6 lists the steady-state voltage and current values expected from Stratix V devices. Power supply ramps must all be strictly monotonic, without plateaus.

Table 6. Recommended Operating Conditions for Stratix V Devices (Part 1 of 2)

Symbol	Description	Condition	Min ⁽⁴⁾	Тур	Max ⁽⁴⁾	Unit
	Core voltage and periphery circuitry power supply (C1, C2, I2, and I3YY speed grades)	_	0.87	0.9	0.93	V
V _{CC}	Core voltage and periphery circuitry power supply (C2L, C3, C4, I2L, I3, I3L, and I4 speed grades) (3)	_	0.82	0.85	0.88	V
V _{CCPT}	Power supply for programmable power technology	_	1.45	1.50	1.55	V
V _{CC_AUX}	Auxiliary supply for the programmable power technology	_	2.375	2.5	2.625	V
V (1)	I/O pre-driver (3.0 V) power supply		2.85	3.0	3.15	V
V _{CCPD} ⁽¹⁾	I/O pre-driver (2.5 V) power supply		2.375	2.5	2.625	V
	I/O buffers (3.0 V) power supply	_	2.85	3.0	3.15	٧
V_{CCIO}	I/O buffers (2.5 V) power supply	_	2.375	2.5	2.625	V
	I/O buffers (1.8 V) power supply	_	1.71	1.8	1.89	٧
	I/O buffers (1.5 V) power supply	_	1.425	1.5	1.575	V
	I/O buffers (1.35 V) power supply		1.283	1.35	1.45	V
	I/O buffers (1.25 V) power supply		1.19	1.25	1.31	V
	I/O buffers (1.2 V) power supply	_	1.14	1.2	1.26	V
	Configuration pins (3.0 V) power supply		2.85	3.0	3.15	V
V_{CCPGM}	Configuration pins (2.5 V) power supply	_	2.375	2.5	2.625	V
	Configuration pins (1.8 V) power supply	_	1.71	1.8	1.89	V
V _{CCA_FPLL}	PLL analog voltage regulator power supply		2.375	2.5	2.625	V
V _{CCD_FPLL}	PLL digital voltage regulator power supply		1.45	1.5	1.55	V
V _{CCBAT} (2)	Battery back-up power supply (For design security volatile key register)	_	1.2	_	3.0	V
V _I	DC input voltage	_	-0.5	_	3.6	V
V ₀	Output voltage	_	0	_	V _{CCIO}	V
т.	Operating junction temperature	Commercial	0	_	85	°C
T _J	Operating junction temperature	Industrial	-40	_	100	°C

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Table 13. OCT Variation after Power-Up Calibration for Stratix V Devices (Part 2 of 2) (1)

Symbol	Description	V _{CCIO} (V)	Typical	Unit		
		3.0	0.189			
		2.5	0.208			
dR/dT	OCT variation with temperature without recalibration	1.8	0.266	%/°C		
	Willout recalibration	1.5	0.273	1		
		1.2	0.317			

Note to Table 13:

(1) Valid for a V_{CCIO} range of $\pm 5\%$ and a temperature range of 0° to $85^\circ\text{C}.$

Pin Capacitance

Table 14 lists the Stratix V device family pin capacitance.

Table 14. Pin Capacitance for Stratix V Devices

Symbol	Description	Value	Unit
C _{IOTB}	Input capacitance on the top and bottom I/O pins	6	pF
C _{IOLR}	Input capacitance on the left and right I/O pins	6	pF
C _{OUTFB}	Input capacitance on dual-purpose clock output and feedback pins	6	pF

Hot Socketing

Table 15 lists the hot socketing specifications for Stratix V devices.

Table 15. Hot Socketing Specifications for Stratix V Devices

Symbol	Description	Maximum
I _{IOPIN (DC)}	DC current per I/O pin	300 μΑ
I _{IOPIN (AC)}	AC current per I/O pin	8 mA ⁽¹⁾
I _{XCVR-TX (DC)}	DC current per transceiver transmitter pin	100 mA
I _{XCVR-RX (DC)}	DC current per transceiver receiver pin	50 mA

Note to Table 15:

(1) The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns, $|I_{IOPIN}| = C dv/dt$, in which C is the I/O pin capacitance and dv/dt is the slew rate.

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Table 18. Single-Ended SSTL, HSTL, and HSUL I/O Reference Voltage Specifications for Stratix V Devices

I/O Standard		V _{CCIO} (V)			V _{REF} (V)			V _{TT} (V)	
I/O Standard	Min	Тур	Max	Min	Тур	Max	Min	Тур	Мах
SSTL-2 Class I, II	2.375	2.5	2.625	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	V _{REF} – 0.04	V_{REF}	V _{REF} + 0.04
SSTL-18 Class I, II	1.71	1.8	1.89	0.833	0.9	0.969	V _{REF} – 0.04	V _{REF}	V _{REF} + 0.04
SSTL-15 Class I, II	1.425	1.5	1.575	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * VCCIO	0.51 * V _{CCIO}
SSTL-135 Class I, II	1.283	1.35	1.418	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}
SSTL-125 Class I, II	1.19	1.25	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * VCCIO	0.51 * V _{CCIO}
SSTL-12 Class I, II	1.14	1.20	1.26	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	0.49 * V _{CCIO}	0.5 * VCCIO	0.51 * V _{CCIO}
HSTL-18 Class I, II	1.71	1.8	1.89	0.85	0.9	0.95	_	V _{CCIO} /2	_
HSTL-15 Class I, II	1.425	1.5	1.575	0.68	0.75	0.9	_	V _{CCIO} /2	_
HSTL-12 Class I, II	1.14	1.2	1.26	0.47 * V _{CCIO}	0.5 * V _{CCIO}	0.53 * V _{CCIO}	_	V _{CCIO} /2	_
HSUL-12	1.14	1.2	1.3	0.49 * V _{CCIO}	0.5 * V _{CCIO}	0.51 * V _{CCIO}	_	_	_

Table 19. Single-Ended SSTL, HSTL, and HSUL I/O Standards Signal Specifications for Stratix V Devices (Part 1 of 2)

I/O Standard	V _{IL(D(}	_{c)} (V)	V _{IH(D}	_{C)} (V)	V _{IL(AC)} (V)	V _{IH(AC)} (V)	V _{OL} (V)	V _{OH} (V)	I (mA)	I _{oh}
i/U Stanuaru	Min	Max	Min	Max	Max	Min	Max	Min	I _{ol} (mA)	(mA)
SSTL-2 Class I	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.608	V _{TT} + 0.608	8.1	-8.1
SSTL-2 Class II	-0.3	V _{REF} – 0.15	V _{REF} + 0.15	V _{CCIO} + 0.3	V _{REF} – 0.31	V _{REF} + 0.31	V _{TT} – 0.81	V _{TT} + 0.81	16.2	-16.2
SSTL-18 Class I	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	V _{TT} – 0.603	V _{TT} + 0.603	6.7	-6.7
SSTL-18 Class II	-0.3	V _{REF} – 0.125	V _{REF} + 0.125	V _{CCIO} + 0.3	V _{REF} – 0.25	V _{REF} + 0.25	0.28	V _{CCIO} - 0.28	13.4	-13.4
SSTL-15 Class I	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCIO}	0.8 * V _{CCIO}	8	-8
SSTL-15 Class II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.175	V _{REF} + 0.175	0.2 * V _{CCIO}	0.8 * V _{CCIO}	16	-16
SSTL-135 Class I, II	_	V _{REF} – 0.09	V _{REF} + 0.09	_	V _{REF} – 0.16	V _{REF} + 0.16	0.2 * V _{CCIO}	0.8 * V _{CCIO}	_	_
SSTL-125 Class I, II	_	V _{REF} – 0.85	V _{REF} + 0.85	_	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}	_	_
SSTL-12 Class I, II	_	V _{REF} – 0.1	V _{REF} + 0.1	_	V _{REF} – 0.15	V _{REF} + 0.15	0.2 * V _{CCIO}	0.8 * V _{CCIO}	_	_

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You typically use the interactive Excel-based Early Power Estimator before designing the FPGA to get a magnitude estimate of the device power. The Quartus II PowerPlay Power Analyzer provides better quality estimates based on the specifics of the design after you complete place-and-route. The PowerPlay Power Analyzer can apply a combination of user-entered, simulation-derived, and estimated signal activities that, when combined with detailed circuit models, yields very accurate power estimates.

For more information about power estimation tools, refer to the *PowerPlay Early Power Estimator User Guide* and the *PowerPlay Power Analysis* chapter in the *Quartus II Handbook*.

Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 4 of 7)

Symbol/	Conditions	Tra	nsceive Grade	r Speed 1	Trai	nsceive Grade	r Speed 2	Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	$\begin{array}{c} \textbf{Unit} \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\ \\$
	85– Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on- chip termination resistors ⁽²¹⁾	100–Ω setting	_	100 ± 30%		_	100 ± 30%	_	_	100 ± 30%	_	Ω
	120–Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC and DC	V _{CCR_GXB} = 0.85 V or 0.9 V full bandwidth	_	600	_	_	600	_	_	600	_	mV
	V _{CCR_GXB} = 0.85 V or 0.9 V half bandwidth	_	600	_	_	600	_	_	600	_	mV
coupled)	$V_{CCR_GXB} = \\ 1.0 \text{ V/1.05 V} \\ \text{full} \\ \text{bandwidth}$	_	700	_	_	700	_	_	700	_	mV
	V _{CCR_GXB} = 1.0 V half bandwidth	_	750	_	_	750	_	_	750	_	mV
t _{LTR} (11)	_	_	_	10	_	_	10	_	_	10	μs
t _{LTD} (12)	_	4	_		4			4			μs
t _{LTD_manual} (13)	_	4	_		4			4			μs
t _{LTR_LTD_manual} (14)		15			15		_	15	_		μs
Run Length		_	_	200	_		200	_	-	200	UI
Programmable equalization (AC Gain) (10)	Full bandwidth (6.25 GHz) Half bandwidth (3.125 GHz)	_	_	16	_	_	16	_	_	16	dB

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description	Conditions	Transceiver Speed Grade 1			Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs

Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{I TD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll\ powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{nll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{REF} is 2000 Ω ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

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Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Mada (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode ⁽²⁾	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

⁽³⁾ The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

Table 26 shows the approximate maximum data rate using the 10G PCS.

Table 26. Stratix V 10G PCS Approximate Maximum Data Rate (1)

Mode (2)	Transceiver	PMA Width	64	40	40	40	32	32			
Widue (2)	Speed Grade	PCS Width	64	66/67	50	40	64/66/67	32			
	1	C1, C2, C2L, I2, I2L core speed grade	14.1	14.1	10.69	14.1	13.6	13.6			
	2	C1, C2, C2L, I2, I2L core speed grade	12.5	12.5	10.69	12.5	12.5	12.5			
	۷	C3, I3, I3L core speed grade	12.5	12.5	10.69	12.5	10.88	10.88			
FIFO or Register		C1, C2, C2L, I2, I2L core speed grade									
	3	C3, I3, I3L core speed grade	8.5 Gbps								
	3	C4, I4 core speed grade									
		I3YY core speed grade			10.312	25 Gbps					

Notes to Table 26:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

Figure 6 shows the Stratix V DC gain curves for GT channels.

Figure 6. DC Gain Curves for GT Channels

Transceiver Characterization

This section summarizes the Stratix V transceiver characterization results for compliance with the following protocols:

- Interlaken
- 40G (XLAUI)/100G (CAUI)
- 10GBase-KR
- QSGMII
- XAUI
- SFI
- Gigabit Ethernet (Gbe / GIGE)
- SPAUI
- Serial Rapid IO (SRIO)
- CPRI
- OBSAI
- Hyper Transport (HT)
- SATA
- SAS
- CEI

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- XFI
- ASI
- HiGig/HiGig+
- HiGig2/HiGig2+
- Serial Data Converter (SDC)
- GPON
- SDI
- SONET
- Fibre Channel (FC)
- PCIe
- QPI
- SFF-8431

Download the Stratix V Characterization Report Tool to view the characterization report summary for these protocols.

Core Performance Specifications

This section describes the clock tree, phase-locked loop (PLL), digital signal processing (DSP), memory blocks, configuration, and JTAG specifications.

Clock Tree Specifications

Table 30 lists the clock tree specifications for Stratix V devices.

Table 30. Clock Tree Performance for Stratix V Devices (1)

	Performance							
Symbol	C1, C2, C2L, I2, and I2L	C3, I3, I3L, and I3YY	C4, I4	Unit				
Global and Regional Clock	717	650	580	MHz				
Periphery Clock	550	500	500	MHz				

Note to Table 30:

(1) The Stratix V ES devices are limited to 600 MHz core clock tree performance.

Table 33. Memory Block Performance Specifications for Stratix V Devices (1), (2) (Part 2 of 2)

		Resour	ces Used			Pe	erforman	ce			
Memory	Mode	ALUTS	Memory	C1	C2, C2L	C3	C4	12, 12L	13, 13L, 13YY	14	Unit
	Single-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	Simple dual-port with the read-during-write option set to Old Data , all supported widths	0	1	525	525	455	400	525	455	400	MHz
M20K Block	Simple dual-port with ECC enabled, 512 × 32	0	1	450	450	400	350	450	400	350	MHz
	Simple dual-port with ECC and optional pipeline registers enabled, 512 × 32	0	1	600	600	500	450	600	500	450	MHz
	True dual port, all supported widths	0	1	700	700	650	550	700	500	450	MHz
	ROM, all supported widths	0	1	700	700	650	550	700	500	450	MHz

Notes to Table 33:

Temperature Sensing Diode Specifications

Table 34 lists the internal TSD specification.

Table 34. Internal Temperature Sensing Diode Specification

Tei	mperature Range	Accuracy	Offset Calibrated Option	Sampling Rate	Conversion Time	Resolution	Minimum Resolution with no Missing Codes
-40°	°C to 100°C	±8°C	No	1 MHz, 500 KHz	< 100 ms	8 bits	8 bits

Table 35 lists the specifications for the Stratix V external temperature sensing diode.

Table 35. External Temperature Sensing Diode Specifications for Stratix V Devices

Description	Min	Тур	Max	Unit
I _{bias} , diode source current	8	_	200	μΑ
V _{bias,} voltage across diode	0.3	_	0.9	V
Series resistance	_	_	<1	Ω
Diode ideality factor	1.006	1.008	1.010	_

⁽¹⁾ To achieve the maximum memory block performance, use a memory block clock that comes through global clock routing from an on-chip PLL set to **50%** output duty cycle. Use the Quartus II software to report timing for this and other memory block clocking schemes.

⁽²⁾ When you use the error detection cyclical redundancy check (CRC) feature, there is no degradation in F_{MAX}.

⁽³⁾ The F_{MAX} specification is only achievable with Fitter options, **MLAB Implementation In 16-Bit Deep Mode** enabled.

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 2 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I4	4	II.a.i.k
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
Transmitter														
	SERDES factor J = 3 to 10 (9), (11), (12), (13), (14), (15), (16)	(6)	_	1600	(6)	_	1434	(6)	_	1250	(6)	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS TX with DPA (12), (14), (15), (16)	(6)	_	1600	(6)	_	1600	(6)	_	1600	(6)		1250	Mbps
- f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
Emulated Differential I/O Standards with Three External Output Resistor Networks - f _{HSDR} (data rate) (10)	SERDES factor J = 4 to 10 (17)	(6)	_	1100	(6)	_	1100	(6)	_	840	(6)		840	Mbps
t _{x Jitter} - True Differential	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	160	_	_	160	_	_	160	_	_	160	ps
I/O Standards	Total Jitter for Data Rate < 600 Mbps	_	_	0.1	_	_	0.1	_	_	0.1	_	_	0.1	UI
t _{x Jitter} - Emulated Differential I/O Standards	Total Jitter for Data Rate 600 Mbps - 1.25 Gbps	_	_	300	_	_	300	_	_	300	_	_	325	ps
with Three External Output Resistor Network	Total Jitter for Data Rate < 600 Mbps	_	_	0.2	_	_	0.2	_	_	0.2	_	_	0.25	UI

Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 4 of 4)

Cumbal	Conditions		C1		C2,	C2L, I	2, I2L	C3,	I3, I3I	., I3YY		C4,I	4	Unit
Symbol	Conuntions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Ullit
	SERDES factor J = 3 to 10	(6)	_	(8)	(6)		(8)	(6)		(8)	(6)	_	(8)	Mbps
f _{HSDR} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)		(7)	(6)		(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	(6)	_	(7)	Mbps
DPA Mode														
DPA run length	_	_	_	1000 0	_		1000 0	_		1000 0	_	_	1000 0	UI
Soft CDR mode	•													
Soft-CDR PPM tolerance	_	_	_	300	_	_	300	_	_	300	_	_	300	± PPM
Non DPA Mode	,													
Sampling Window	_	_	_	300	_		300	_		300	_	_	300	ps

Notes to Table 36:

- (1) When J = 3 to 10, use the serializer/deserializer (SERDES) block.
- (2) When J = 1 or 2, bypass the SERDES block.
- (3) This only applies to DPA and soft-CDR modes.
- (4) Clock Boost Factor (W) is the ratio between the input data rate to the input clock rate.
- (5) This is achieved by using the **LVDS** clock network.
- (6) The minimum specification depends on the clock source (for example, the PLL and clock pin) and the clock routing resource (global, regional, or local) that you use. The I/O differential buffer and input register do not have a minimum toggle rate.
- (7) The maximum ideal frequency is the SERDES factor (J) x the PLL maximum output frequency (fOUT) provided you can close the design timing and the signal integrity simulation is clean.
- (8) You can estimate the achievable maximum data rate for non-DPA mode by performing link timing closure analysis. You must consider the board skew margin, transmitter delay margin, and receiver sampling margin to determine the maximum data rate supported.
- (9) If the receiver with DPA enabled and transmitter are using shared PLLs, the minimum data rate is 150 Mbps.
- (10) You must calculate the leftover timing margin in the receiver by performing link timing closure analysis. You must consider the board skew margin, transmitter channel-to-channel skew, and receiver sampling margin to determine leftover timing margin.
- (11) The F_{MAX} specification is based on the fast clock used for serial data. The interface F_{MAX} is also dependent on the parallel clock domain which is design-dependent and requires timing analysis.
- (12) Stratix V RX LVDS will need DPA. For Stratix V TX LVDS, the receiver side component must have DPA.
- (13) Stratix V LVDS serialization and de-serialization factor needs to be x4 and above.
- (14) Requires package skew compensation with PCB trace length.
- (15) Do not mix single-ended I/O buffer within LVDS I/O bank.
- (16) Chip-to-chip communication only with a maximum load of 5 pF.
- (17) When using True LVDS RX channels for emulated LVDS TX channel, only serialization factors 1 and 2 are supported.

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Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)
Stratix V E (1)	5SEE9	_	342,742,976	700,888
Stratix V L 17	5SEEB	_	342,742,976	700,888

Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Banker		Active Serial (1))	Fas	t Passive Parall	el ⁽²⁾
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
	A3	4	100	0.534	32	100	0.067
	AS	4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
GX	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	В9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
G1	C7	4	100	0.675	32	100	0.084

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Table 50 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA[] ratio is 1.

Table 50. FPP Timing Parameters for Stratix V Devices (1)

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nCONFIG low to CONF_DONE low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μ\$
t _{CF2ST1}	nCONFIG high to nSTATUS high	_	1,506 ⁽³⁾	μ\$
t _{CF2CK} (6)	nCONFIG high to first rising edge on DCLK	1,506	_	μ\$
t _{ST2CK} (6)	nSTATUS high to first rising edge of DCLK	2	_	μ\$
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	0	_	ns
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _{CD2UM}	CONF_DONE high to user mode (4)	175	437	μS
+	GOVER DOVER high to GUVERN anabled	4 × maximum		
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁵⁾	_	_

Notes to Table 50:

- (1) Use these timing parameters when the decompression and design security features are disabled.
- (2) This value is applicable if you do not delay configuration by extending the nCONFIG or nSTATUS low pulse width.
- (3) This value is applicable if you do not delay configuration by externally holding the nstatus low.
- (4) The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.
- (5) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

FPP Configuration Timing when DCLK-to-DATA [] > 1

Figure 13 shows the timing waveform for FPP configuration when using a MAX II device, MAX V device, or microprocessor as an external host. This waveform shows timing when the DCLK-to-DATA [] ratio is more than 1.

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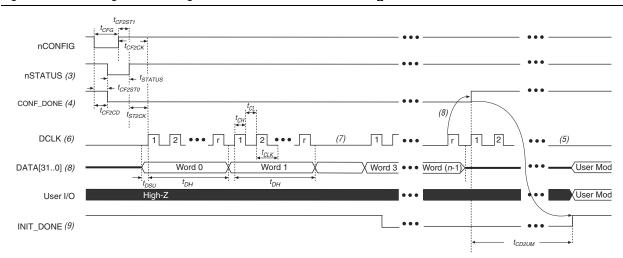


Figure 13. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is >1 (1), (2)

Notes to Figure 13:

- (1) Use this timing waveform and parameters when the DCLK-to-DATA [] ratio is >1. To find out the DCLK-to-DATA [] ratio for your system, refer to Table 49 on page 55.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nconfig, nstatus, and conf_done are at logic high levels. When nconfig is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time as specified by the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (6) "r" denotes the DCLK-to-DATA[] ratio. For the DCLK-to-DATA[] ratio based on the decompression and the design security feature enable settings, refer to Table 49 on page 55.
- (7) If needed, pause DCLK by holding it low. When DCLK restarts, the external host must provide data on the DATA [31..0] pins prior to sending the first DCLK rising edge.
- (8) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (9) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 $^{(1)}$

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nconfig high to nstatus high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾	_	S
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _R	Input rise time	_	40	ns
t _F	Input fall time	_	40	ns
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nSTATUS is monitored, follow the t_{ST2CK} specification. If nSTATUS is not monitored, follow the t_{CF2CK} specification.

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Active Serial Configuration Timing

Table 52 lists the DCLK frequency specification in the AS configuration scheme.

Table 52. DCLK Frequency Specification in the AS Configuration Scheme (1), (2)

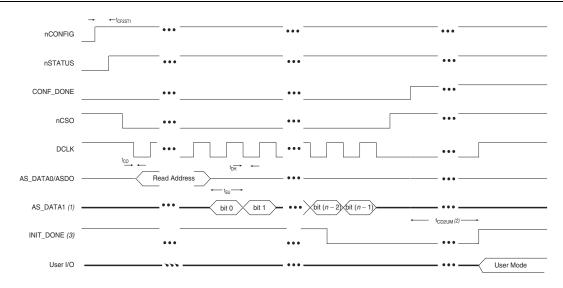
Minimum	Typical	Maximum	Unit
5.3	7.9	12.5	MHz
10.6	15.7	25.0	MHz
21.3	31.4	50.0	MHz
42.6	62.9	100.0	MHz

Notes to Table 52:

- (1) This applies to the DCLK frequency specification when using the internal oscillator as the configuration clock source.
- (2) The AS multi-device configuration scheme does not support DCLK frequency of 100 MHz.

Figure 14 shows the single-device configuration setup for an AS ×1 mode.

Figure 14. AS Configuration Timing



Notes to Figure 14:

- (1) If you are using AS ×4 mode, this signal represents the AS_DATA [3..0] and EPCQ sends in 4-bits of data for each DCLK cycle.
- (2) The initialization clock can be from internal oscillator or ${\tt CLKUSR}$ pin.
- (3) After the option bit to enable the $INIT_DONE$ pin is configured into the device, the $INIT_DONE$ goes low.

Table 53 lists the timing parameters for AS $\times 1$ and AS $\times 4$ configurations in Stratix V devices.

Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 1 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CO}	DCLK falling edge to AS_DATAO/ASDO output	_	2	ns
t _{SU}	Data setup time before falling edge on DCLK	1.5	_	ns
t _H	Data hold time after falling edge on DCLK	0	_	ns

Page 66 Glossary

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions	
G			
Н	_	_	
1			
J	JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI TCK TJPSU TJ	
K L M N	_		
P	PLL Specifications	Diagram of PLL Specifications (1) Switchover CLKOUT Pins Four Core Clock Reconfigurable in User Mode External Feedback Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.	
Q	_	-	
R	R _L	Receiver differential input discrete resistor (external to the Stratix V device).	
	L		